



Laser Grinding System

The Laser MicroJet®



Cold Laser Power for:
Cutting, Grinding,
Drilling, Grooving and
Scribing

Contained within a hair-thin water jet through total internal reflection, the Laser MicroJet® beam surpasses today's laser and water cutting technologies.

During machining, the work pieces are cooled by the water jet at the cutting interface, resulting in "cold laser cutting", with little or no thermal damage and very few material changes.

At the same time, low water jet pressure ensures that virtually no mechanical force is exerted during processing, allowing rapid, damage-free production of delicate and composite parts.

As a result, the Laser MicroJet® achieves a precise cut over the entire depth of the work piece, leaving a fine, clean surface.

This exceptionally high quality of cut is made possible by the long working distance and constantly focused parallel laser beam.

In the field of high-precision machining of sensitive materials, stringent requirements for fine and small structures demand a new process: Laser MicroJet® is the solution.

Choose Laser MicroJet® and expand your micro-machining capabilities today.

Founded in 1997, Synova is an experienced supplier of state-of-the-art laser solutions for industrial micro-machining applications, serving the semiconductor, electronic and medical markets. Each Synova machine features the unique Laser MicroJet® technology which was invented by Synova. With its headquarters in Lausanne, Switzerland, Synova is a privately owned company with subsidiaries in North America and in the Asia/Pacific region.





Discover the Synova